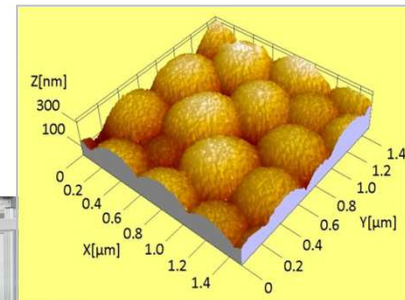
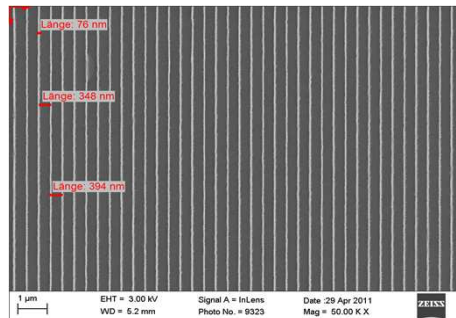


Nano- and Micro Injection Moulding of polymer, metal, and ceramic components for various applications

Volker Piotter

INSTITUTE FOR APPLIED MATERIALS - MATERIALS PROCESS TECHNOLOGY (IAM – WPT)

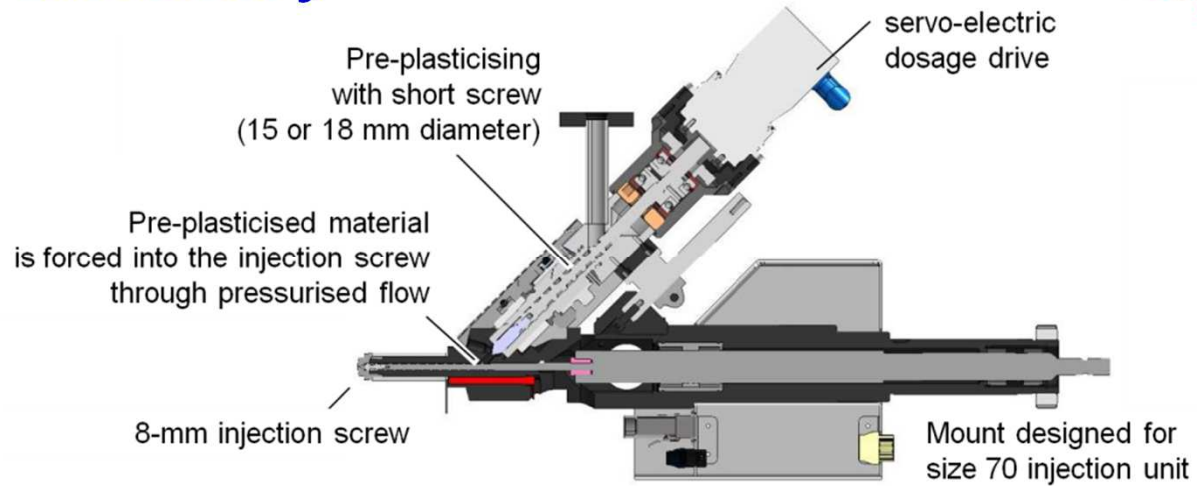


Content

- Machinery and process
- Submicron- and Nano Injection Moulding
- Micro Powder Injection Moulding
- 2-Component Micro Powder Injection Moulding (2C-MicroPIM)
- Summary and Outlook

Machinery

Arburg
micro module

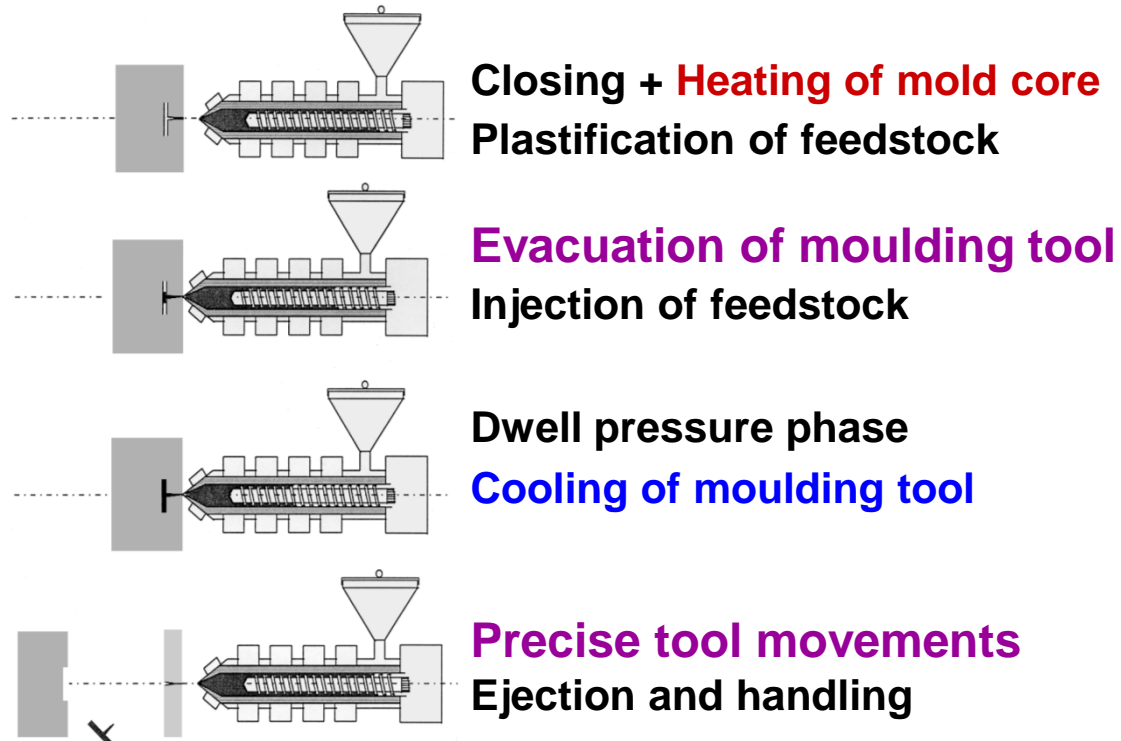


Wittmann Battenfeld MicroPower

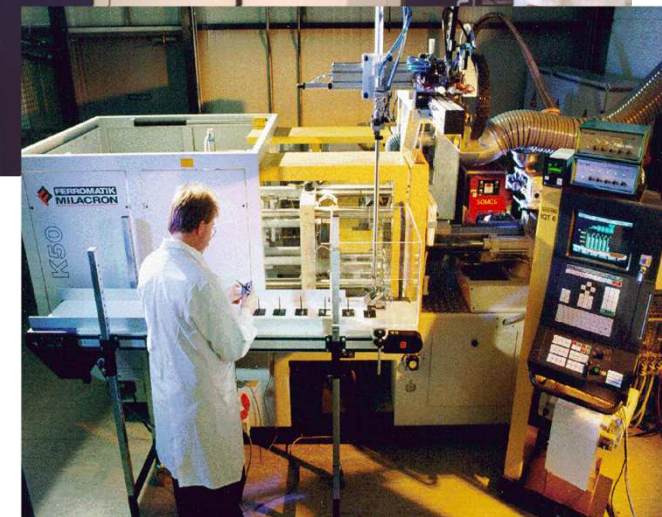


DESMA FormicaPlast 2C

Specialities



Heating / Cooling = Variotherm-process
necessary for replication of high aspect ratios



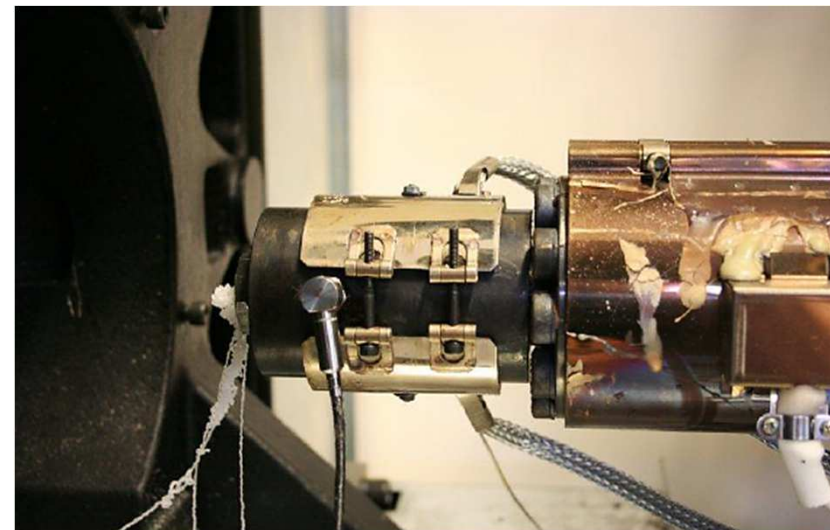
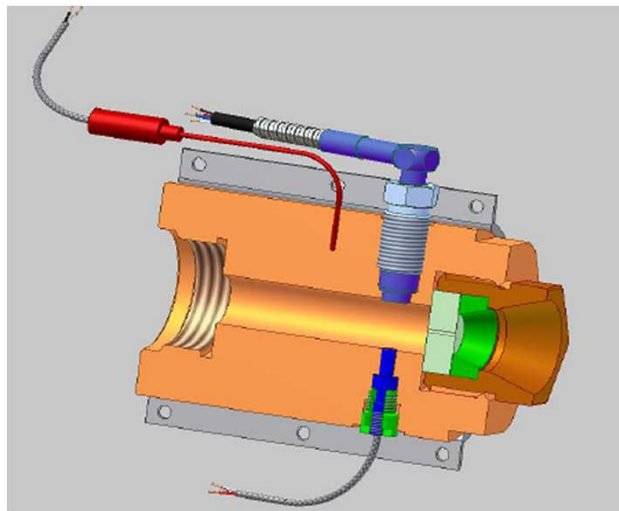
Rheology Investigations



Standard capillary rheometry tests are used to characterise shear flow of materials to around $100\,000\text{s}^{-1}$.

Bradford University converted an injection moulding machine into a rheometer which is capable of withstanding very high pressures (2800bar) and provides high injection velocities.

This allows testing of materials to wall shear rates in excess of $10\,000\,000\text{s}^{-1}$.

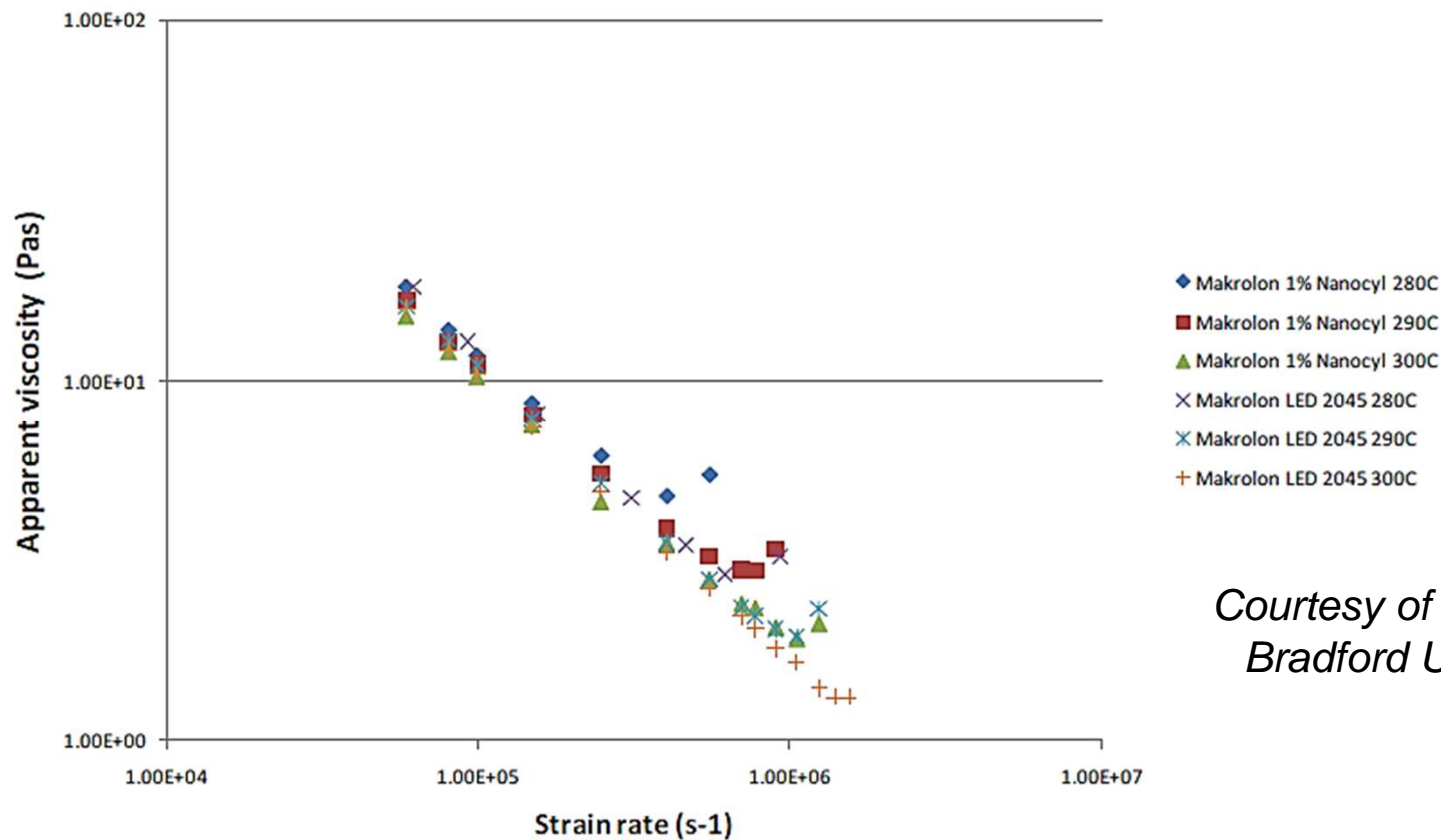


Rheology Investigations



Shear thinning behaviour occurs until a critical limit above which the viscosity will rise significantly.

If a process is operating beyond this point, reducing the injection speed will actually help to fill the cavity.



*Courtesy of Ben Whiteside
Bradford University, UK*

Multi-scale micro/nano manufacture



Al 99.999% Substrate



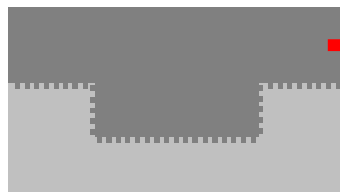
Micromachining



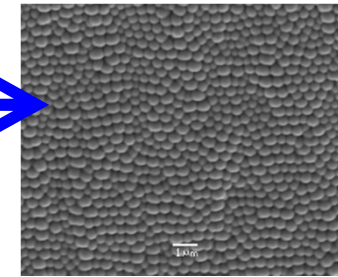
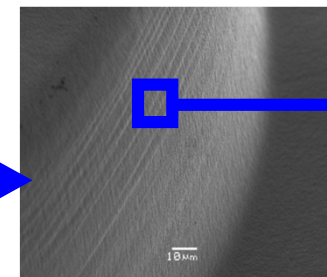
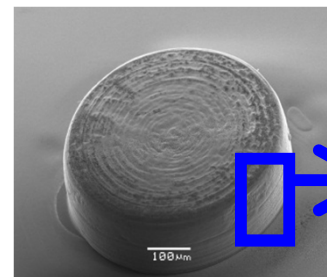
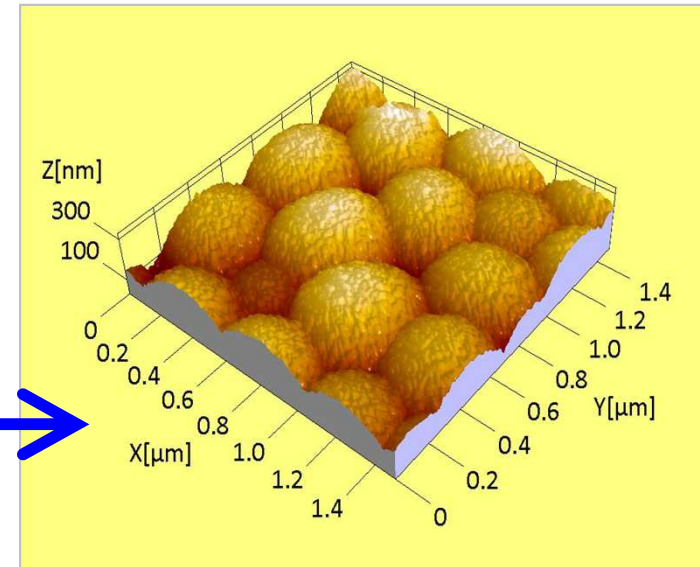
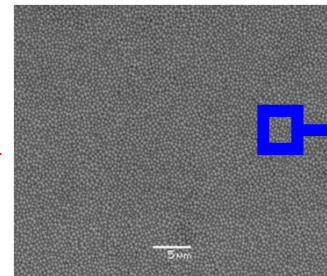
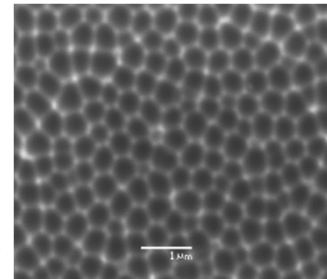
Anodization



Ni Electroplating



Selective etching
(Al dissolution)

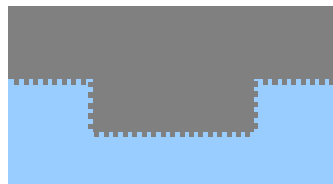


Leap to mass fabrication => injection moulding

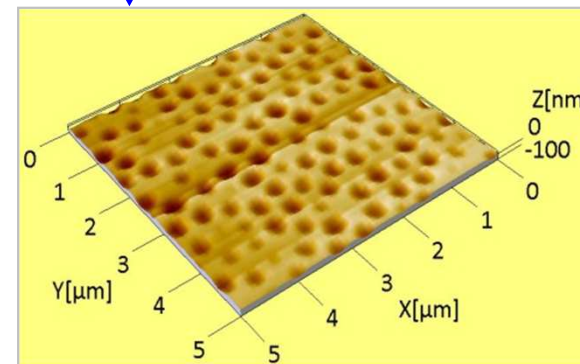
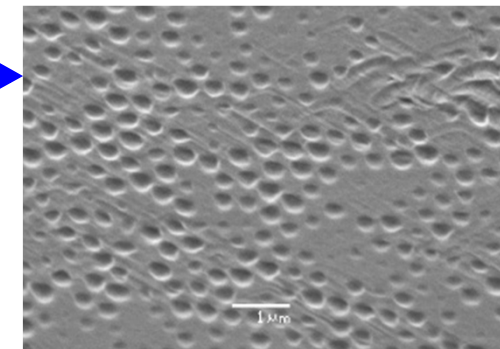
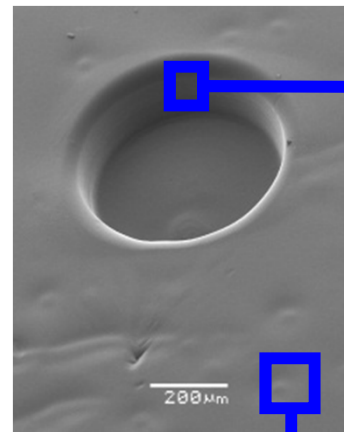
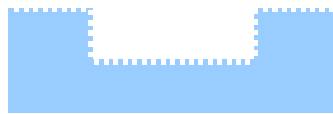
Multi-scale micro/nano manufacture



Injection Moulding



Micro-Nano
Structured
Polymer Part



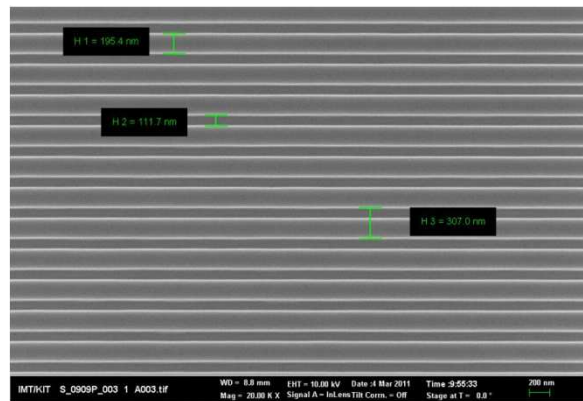
*Courtesy of Guido Tosello,
Technical University of Denmark*

Nano Injection Moulding

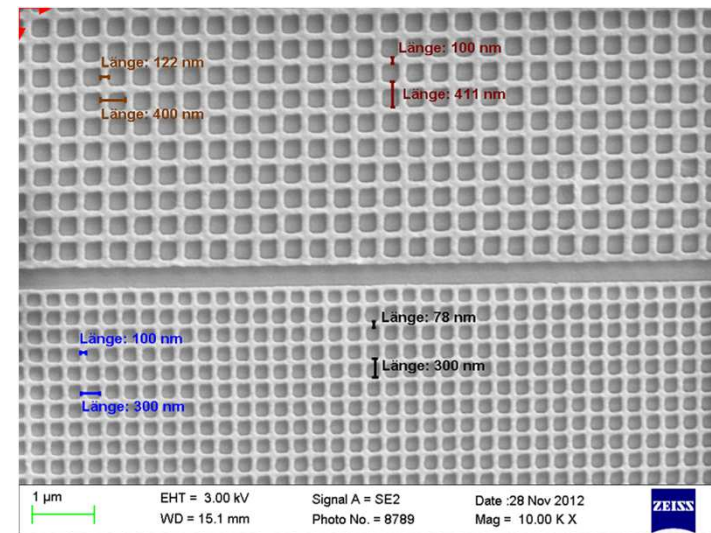
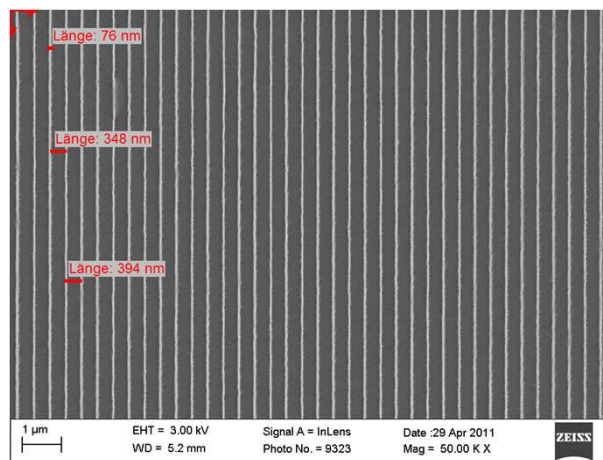
Generation of nano-sized photonic crystal structures for surface contrast microscopy



Kiel University
Y. Nazirizadeh

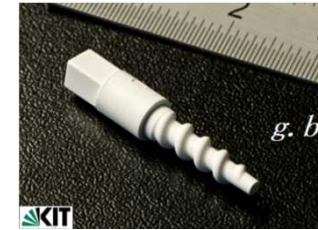
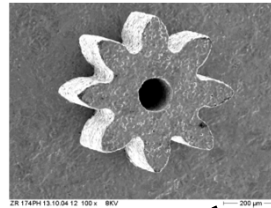


SEM figure of mold insert made by e-beam writing and electroplating (KIT-IMT)



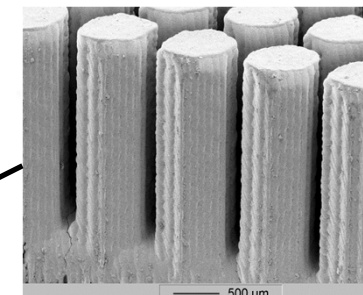
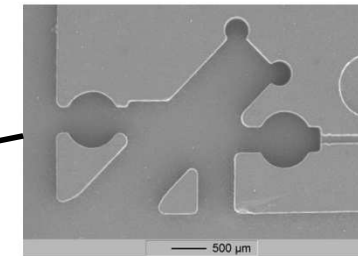
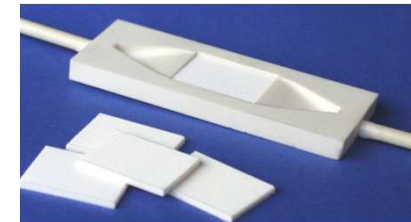
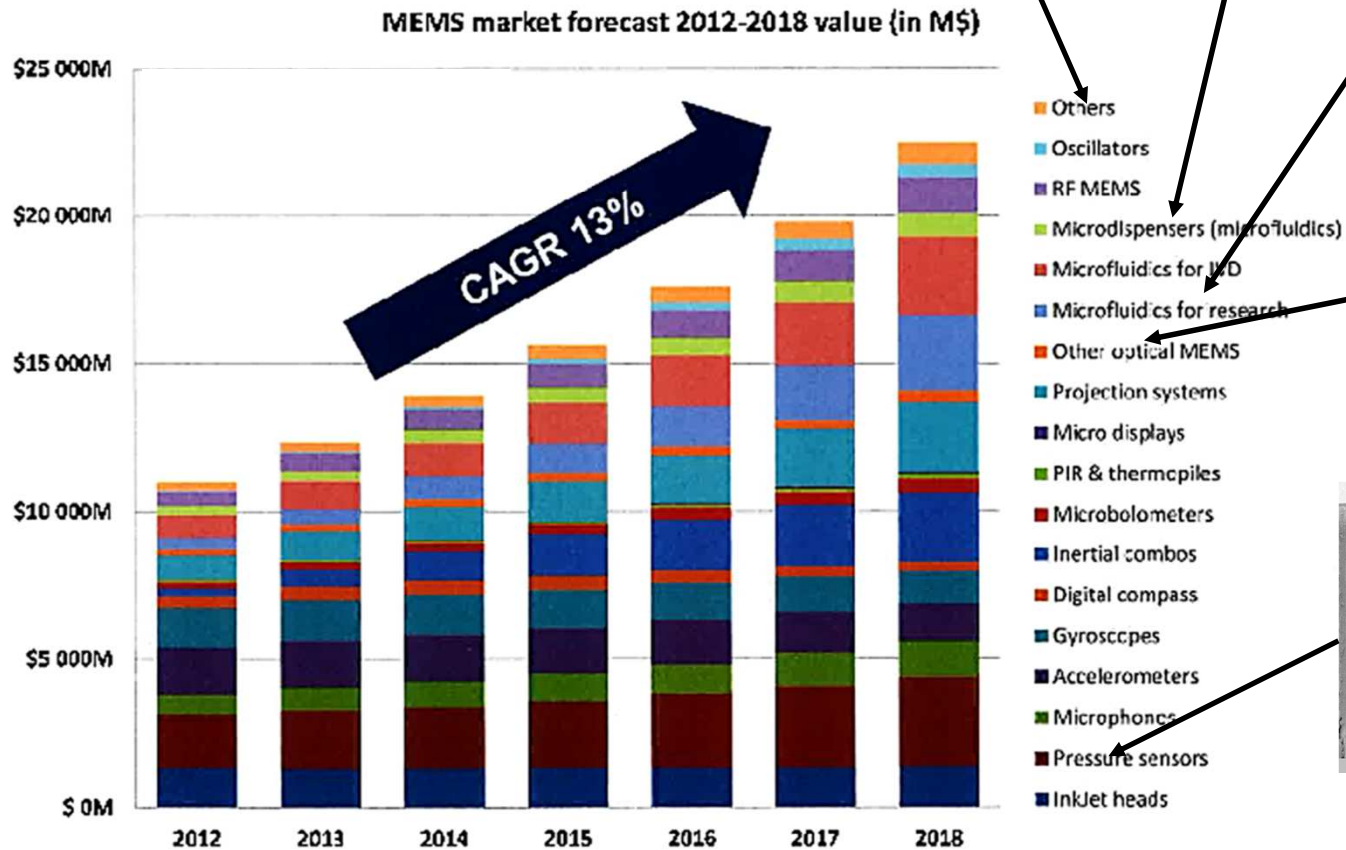
replication in the nm-range
minimum width ca. 80nm, PMMA

Micro System Technology



Source: Yole Development, March 2013

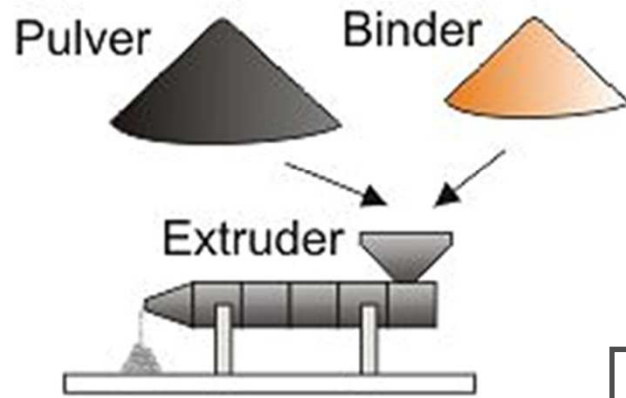
Continued Strong Growth 2012-2018 Forecast (in US\$M)



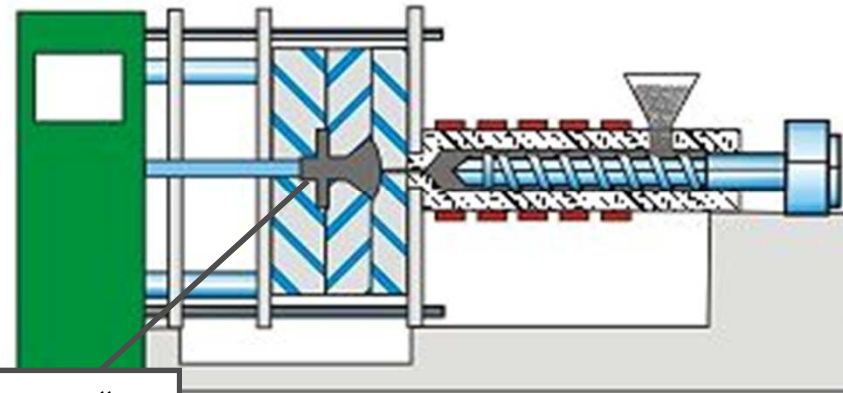
Micro Powder Injection Moulding

© www.pulverspritzgiessen.de

Feedstock preparation



Injection molding

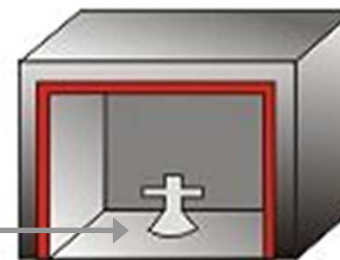


„green“
body

Debinding



Sintering

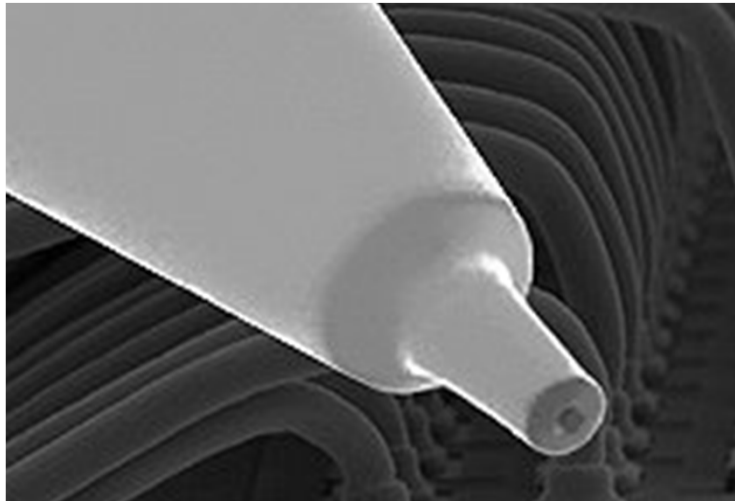


PIM-Materials (selection)

Metal	temp	<p>Micro gear wheels for watches, outer- Ø ca. 1.4mm, modulus 0.1, 42CrMo4, Parmaco Metal Injection Molding AG, CH</p>	
	case-h		
	t		
	stai		
	austenitic		404)
	precipitation		4542)
	low-		
	softmag		3
	t		
	ys	NiCr 22 Fe 18 Mo, NiCr 20 Co 18 Ti	
	S	W, W-La ₂ O ₃ , WNiFe, WCu10, MoNb13, Mo20Cu	
	S	WCxCo, TiN	
		Mo-Al ₂ O ₃ , Fe-TiC	
	S	Al ₂ O ₃ , ZrO ₂ , ZTA, ATZ	
	CS	Si ₃ N ₄ , SiC, AlN	
	CS	PZT, TiN	

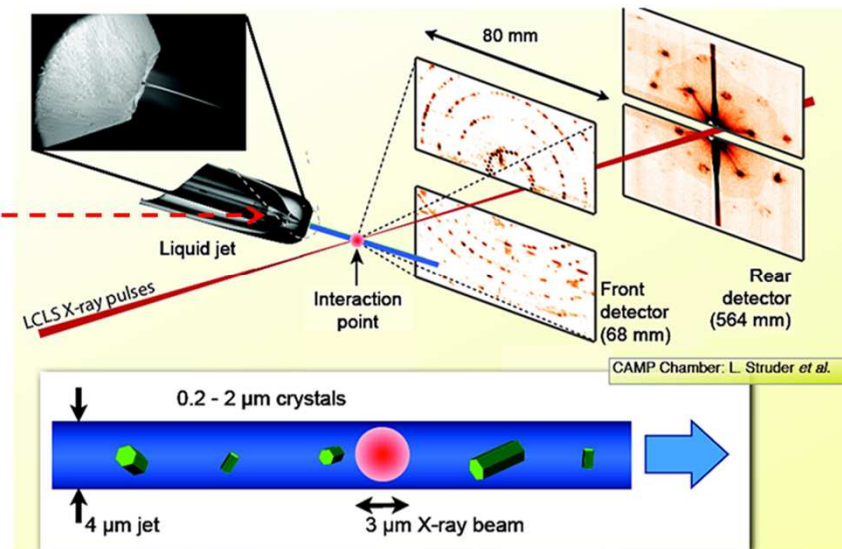
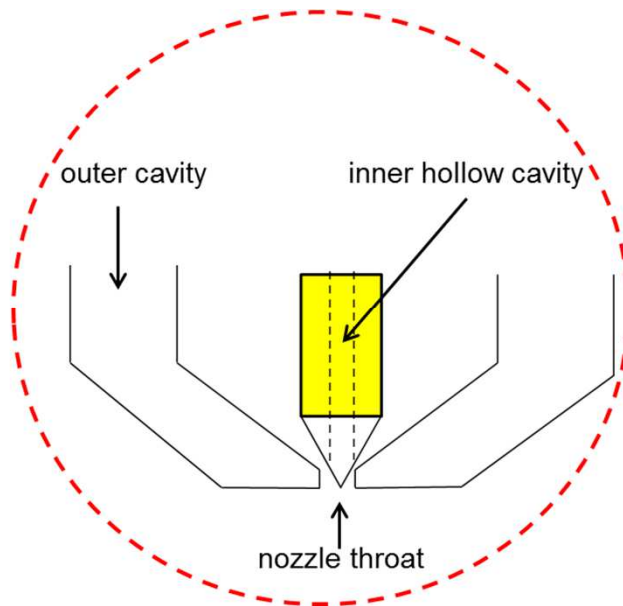


MicroPIM



Capillary for fine pitch bonding
tip- $\varnothing=45\mu\text{m}$, hole- $\varnothing=19\mu\text{m}$
SPT Roth Ltd., CH

Scientific application: liquid jet nozzles for CFEL
collaborative project between DESY and KIT



Micro Injection Moulding – General Data

Materials	min. lat. Dimension [µm]	min. Detail [µm]	Aspect Ratio [isolated walls]	Tolerance [± %]	Roughness ** R _{max} / R _a [µm]	Materials tested
Plastics	10	<0.1	>20 (200*)	0.05	0.05 / <0.05	Thermoplastics, TPE
Metals	50	10	>10	< 0.5	7 / 0.8	17-4PH, 316L, Cu, W, W-alloys
Ceramics	<10	<3	<15	(0.1***) / 0.3	<3 / <0.3	ZrO ₂ , Al ₂ O ₃ , ZTA, Al ₂ O ₃ /TiN, Si ₃ N ₄

* flow length to wall thickness ratio

** depending on mould insert

*** after thorough process optimization

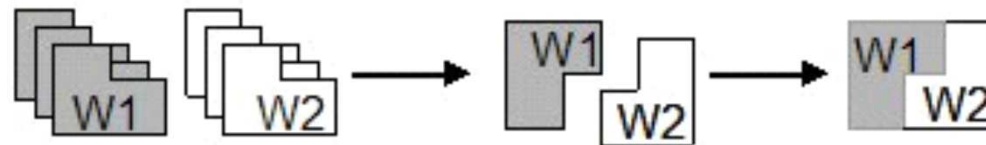
Multi-Component Micro Powder Injection Moulding

Functions integration by combining different materials

Realization of **(im-)mobile** connections

Reduction of **handling** and **assembly expenditure**

single-piece fabrication
+ assembly



2C-MicroPIM
– assembly



Multifunctional- / Multimaterial Products

with **complimentary** or **contradictionary properties**, e.g.

conductive

↔

insulating

hard

↔

tough

magnetic

↔

non-magnetic

hydrophilic

↔

hydrophobic

tight

↔

porous

→ **2-Component MicroPIM (2C-MicroPIM)**

2-Component PIM



Fraunhofer Institute, IFAM

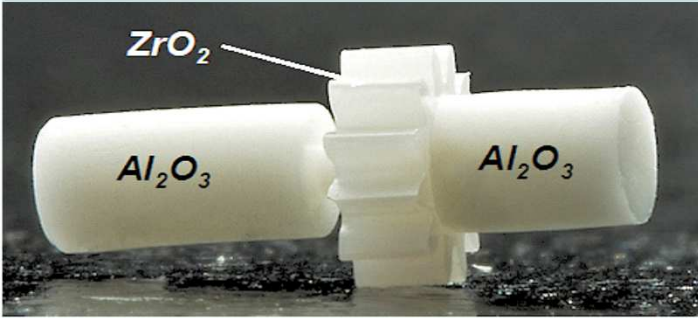
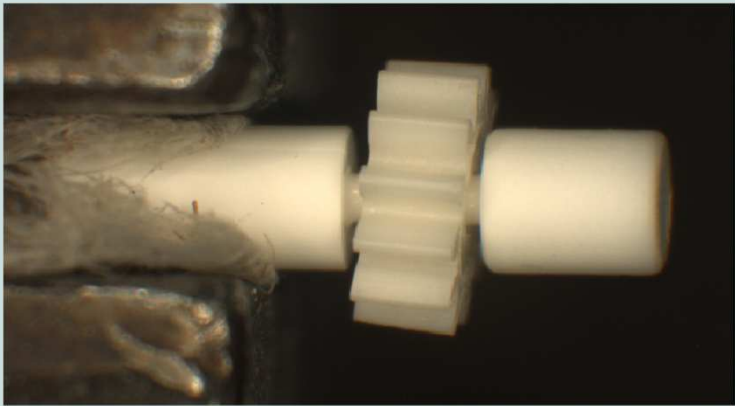
Combination of a magnetic steel (17-4PH) with a non-magnetic steel (316L)

Hard metal WCxCo with different Co-contents (16% and 6%)
ARBURG



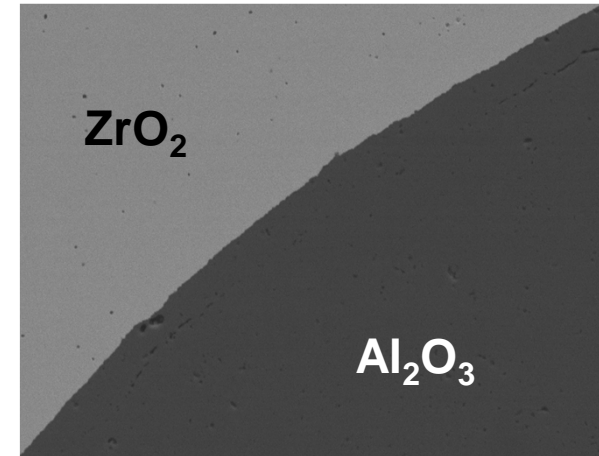
2-Component MIM, steel
AMT, Singapore

2-Component PIM

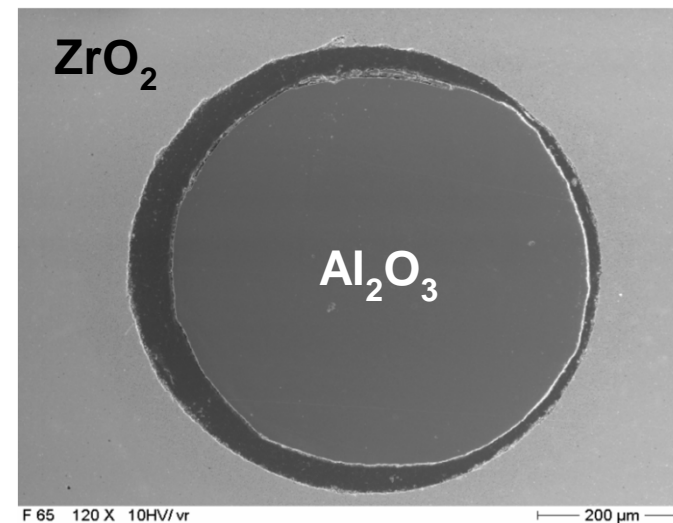
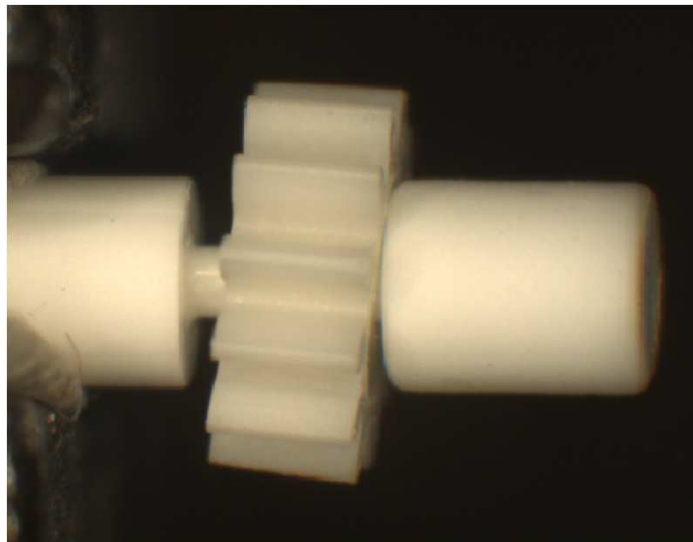
connection	fixed	movable
binders	compatible	not relevant
powder loading	nearly equal	$\varphi_{\text{outside}} > \varphi_{\text{inside}}$
sintering-T	nearly equal	$T_{\text{outside}} > T_{\text{inside}}$
CTE	nearly equal	nearly equal
		

2C-MicroPIM

Fixed connections of different ceramics



Realisation of **movable** connections



Summary and Outlook

- Enhancing **technical performance**

larger variety of materials, e.g. nanopowders

improve simulation/predictability

=> talk of Mr. Marhoefer

thermal contact resistance



resistance to heat flow across the melt/mould interface

- Improving **economic efficiency**

flexible machinery

saving of material and energy

Summary and Outlook

- Enhanced **multi-component** process variants

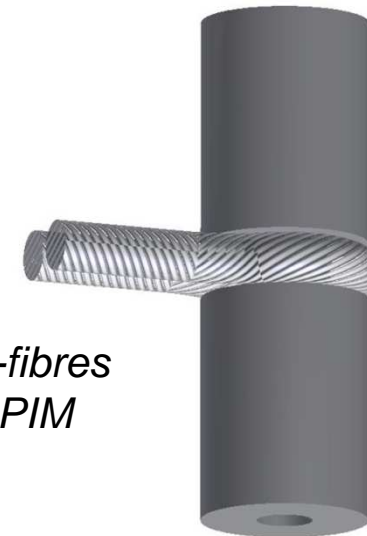
two-component micro injection moulding

sinter-joining of PIM green bodies

=> talk of Mrs. Klimscha

insert powder injection moulding

*Lightweight applications:
material compounds of C-fibres
and metal insert parts by PIM*



Summary and Outlook

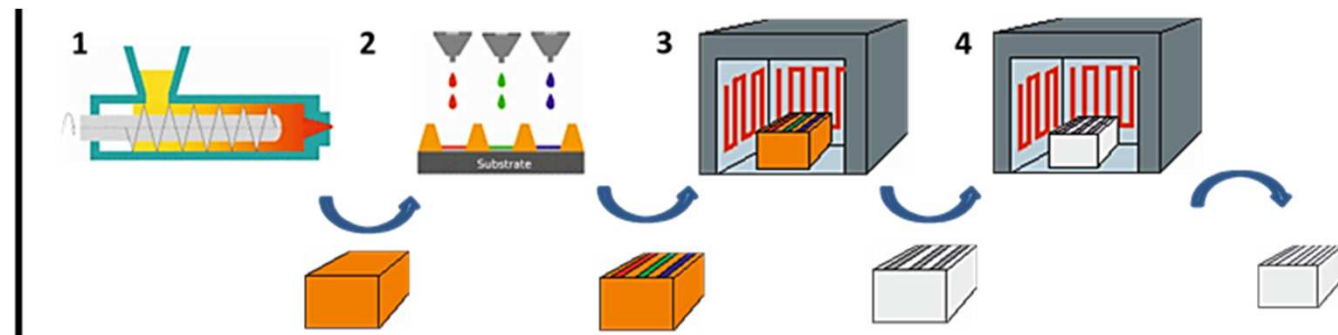
- Hybridization of micro processing technologies

3D-MID and variants

=> *talk of Prof. Hansen*

PIM + Additive Manufacturing

1. Micro PIM
2. 3D inkjet printing
3. Debinding
4. Sintering



Acknowledgment

- **Bradford University**
- **Technical University of Denmark**
- **BMBF and State of Baden-Wuerttemberg**
- **DESY**
- **Deutsche Forschungsgemeinschaft DFG**
- **Companies Arburg, Wittmann Battenfeld, DESMA
RKT, SPT Roth, OBE, Parmaco etc.**
- **All colleagues at KIT** S. Antusch, N. Denker, T. Hanemann, J. Heneka,
P. Holzer, E. Honza, A. Klein, T. Müller, K. Plewa, H. Walter

Thank you !